





UPB496A - PRELIMINARY

4940-4990MHz UPB Series TDD Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade single-band TDD Pico-cell basestations for 0.25-0.5W at the antenna port.

Part Dimensions: $10.3 \times 4.7 \times 4.1 \text{ mm} \cdot < 0.55 \text{ g}$ Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	2.0 Watt max
Peak Input Power	-	-	-	20 Watt max
Input-Output Response Passband Insertion Loss (5 MHz avg)	4940-4990	1.4 dB	1.7 dB max	1.7 dB max
Passband Ripple	4940-4990	0.4 dB	0.7 dB max	0.7 dB max
Passband Return Loss	4940-4990	14 dB	12 dB min	12 dB min
Attenuation:	1-4740		30 dB min	30 dB min
	5150-7125		30 dB min	30 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

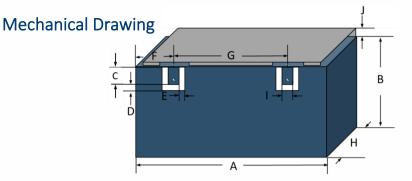
Specification Allowance				
Insertion Loss	0.1 dB			
Return Loss	1.0 dB			
Attenuation	1.0 dB			

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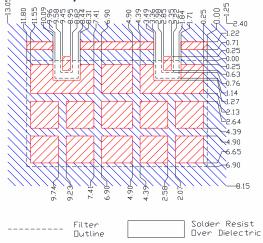
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Dim.	Nominal (mm)	Tolerance (±mm or Max)
Α	10.20	0.13
В	3.20	0.30
С	0.76	0.13
D	0.38	0.13
Е	0.38	0.13
F	1.80	0.13
G	6.60	0.13
Н	3.80	0.30
I	0.76	0.13
J	0.90	0.30

PCB Layout



Exposed

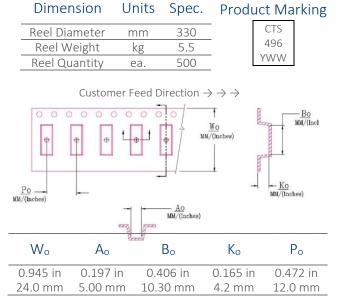
IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Packaging and Marking

Solder Resist Over Conductor



Electrical Response -10 -20 -30 -40 -50 -60 -70 -80 4500 4750 5000 5250 6000 Frequency [MHz] Marker Freq[MHz] 4740 4940 4965 4990 5150 ■ S21[dB](1) -39.3 -33.6

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